LN58

GaAs Infrared Light Emitting Diode

For optical control systems

■ Features

- High-power output, high-efficiency: P_O = 3.5 mW (typ.)
- Emitted light spectrum suited for silicon photodetectors
- Infrared light emission close to monochromatic light: $\lambda_P = 950 \text{ nm}$ (typ.)
- Small size, thin side-view type package

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	75	mW	
Forward current	I_{F}	50	mA	
Pulse forward current *	I_{FP}	1	A	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-25 to +85	°C	
Storage temperature	T _{stg}	-30 to +100	°C	

Note) *: f = 100 Hz, Duty cycle = 0.1%

■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Radiant power *	P _O	$I_F = 50 \text{ mA}$	1.8	3.5		mW
Reverse current	I_R	$V_R = 3 V$			10	μΑ
Forward voltage	V_{F}	$I_F = 50 \text{ mA}$			1.5	V
Terminal capacitance	Ct	$V_R = 0 \text{ V, } f = 1 \text{ MHz}$		35		pF
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 50 \text{ mA}$		950		nm
Spectral half band width	Δλ	$I_F = 50 \text{ mA}$		50		nm
Half-power angle	θ	The angle when the radiant power is halved.		35		0

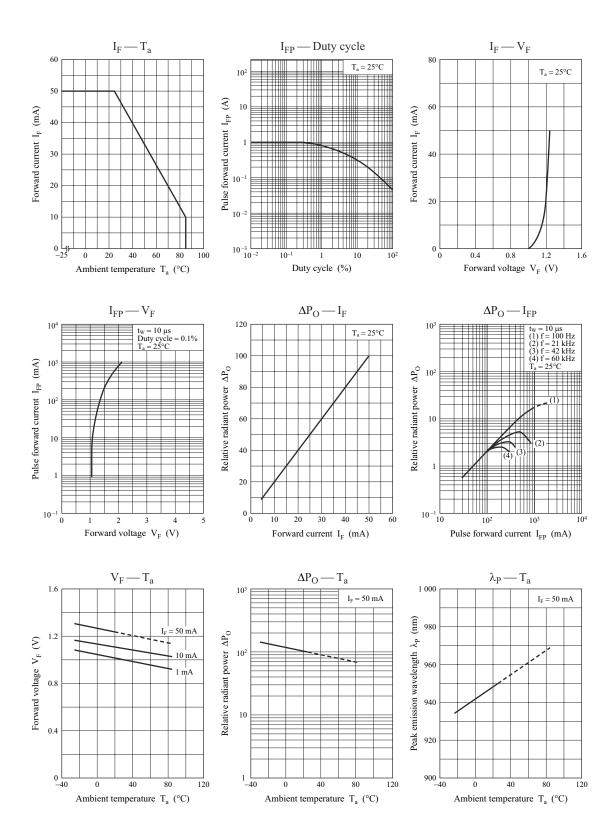
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Cutoff frequency: 1 MHz

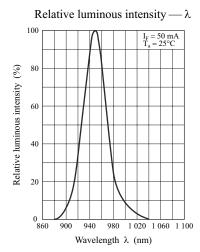
$$f_C$$
: $10 \times log \frac{P_O \text{ at } f = f_C}{P_O \text{ at } f = 50 \text{ kHz}} = -3$

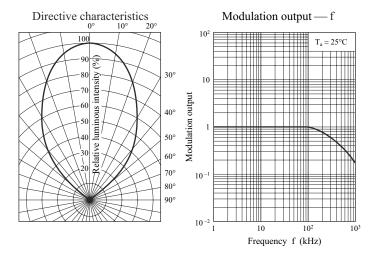
3. *: A light detection element uses a silicon diode have proofread a load with a standard device.

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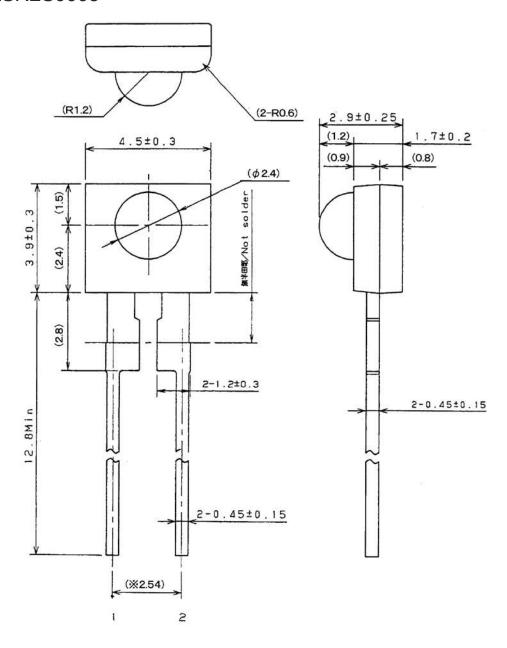




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■ Package (Unit: mm)

LETLSN2S0003



- Pin name
 - 1: Cathode
 - 2: Anode

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